



Final Call For Papers

2019 13th IEEE International Conference on ASIC

Oct. 29-Nov.1, 2019, Hilton Chongqing, Chongqing, China

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Contact persons:

Prof. Huihua Yu

asicon.org

huihua@fudan.edu.cn

(about conference)

Prof. FanYe

fanYe@fudan.edu.cn

(about program)

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2019 13th IEEE International Conference on ASIC (ASICON 2019) will be held in Chongqing, China, during Oct.29-Nov.1, 2019. The conference is intended to provide an international forum for Integrated circuit designers, ASIC users, system integrators, IC manufacturers, process and device engineers, and CAD/CAE tool developers to present their latest progress, development and research results in their respective fields. The four-day event features keynote speeches, invited talks, regular paper presentations and tutorials, delivered by leading experts in the respective fields, on state-of-the-art Integrated circuits, design methodologies, devices, processes and manufacturing technologies. The Excellent Student Paper award will be announced at the conference. Additionally, an exhibition on EDA tools, foundry technologies, IC processing/testing facilities, and novel ASIC products will be held during the conference.

The Scope of the Conference

Papers are solicited in, but not limited to, the following:

I. Integrated Circuits and Design Techniques

[1] Analog IC [2] Digital IC [3] Wireless, Wireline telecommunication and Optic Communication IC [4] Memory [5] Sensor, Image Processing and Bio-medical IC [6] FPGA and DSP [7] Special application IC [8] Design for Testing

II. CAD Techniques

[9] Circuits Simulation, Synthesis, Verification and Physical Design
[10] CAD for System, Design for Manufacturing and Testing

III. New Techniques, New Processing, New Devices and Their Applications

[11] MEMS Techniques [12] Nanoelectronics and Gigascale Systems
[13] New Devices: Heterojunction Devices, Fin FET, CNT MTJ Devices, 3-D Integration, etc. [14] New Processing: Advanced Interconnection Technology, High-K/Metal, Gate Technology and Other VLSI New Processing
[15] Processing Modeling & Simulation

IV. Other VLSI Design and Device Related Topics

[16] Other Devices Related Topics [17] Other VLSI Design Related Topics

Papers Submission

Prospective authors are requested to submit full-length papers in English of no more than four pages using the proceedings format, double columned, 10pt fonts including figures, tables and references. For further information on the paper format, please refer to "[template](#)". The papers are submitted in their final form, if accepted, will be published as submitted. All submissions must be made at the conference website. Student authors, who want to compete for the Excellent Student Paper Award, should apply at the conference website. Detailed instructions for paper preparation and submission can be found at conference website.

Deadline of papers submittal is June 30, 2019

Paper acceptance/rejection will be informed by Aug. 15, 2019

Website: www.asicon.org